

Title (en)
ELECTROLYTIC COPPER PLATING SOLUTIONS AND A METHOD FOR THEIR APPLICATION

Publication
EP 0107109 B1 19880224 (EN)

Application
EP 83109814 A 19830930

Priority
US 42905582 A 19820930

Abstract (en)
[origin: EP0107109A2] Acid copper electroplating solutions containing the reaction product of (1) a compound of the formula <CHEM> wherein R1 and R2 are lower alkyl radicals of with 1 to 6 carbon atoms, a hydrogen atom or mixtures thereof and R4 is an alkali metal, hydrogen, magnesium, or the groups SX or SSX, wherein X is an alkali metal, hydrogen or magnesium, or a compound of the formula <CHEM> wherein R3 is an aromatic, heterocyclic or alicyclic radical containing 3 to 12 carbon atoms and R4 is an alkali metal, hydrogen, magnesium, or the groups SX or SSX where X is an alkali metal, hydrogen or magnesium, (2) a compound of the formula XR1-(S)n-R2-SO3H wherein R1 and R2 are the same or different and are alkylene radicals containing 1 to 6 carbon atoms, X is hydrogen or -SO3H and n equals 2 to 5, and (3) acrylamide in a sufficient amount to increase the brightness of the deposit and/or to prevent the formation of cracks during thermal shock.

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IPC 8 full level
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CPC (source: EP)
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Cited by
WO2006094755A1; EP1568802A4; DE4032864A1; DE19758121A1; DE19758121C2; EP0297306A1; AT396946B; DE10337669A1; DE10337669B4; US7771835B2; US8114263B2

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